layer, plating said conductive material contact layer on said resilient material contact layer, and removing the sacrificial material layer;

a stop structure including a stop surface spaced from said outwardly facing surface, said outwardly facing surface defining a plane spaced from said outwardly facing surface and parallel thereto;

said resilient contact element including an elongated contact structure extending from said proximal end portion, said elongated contact structure providing a distal end portion of said resilient contact element; and

said distal end portion being movable relative to said outwardly facing surface about said proximal end portion through said plane defined by said stop surface.

44. (New) The interconnect assembly according to claim 43, further comprising a plurality of said resilient contact elements, wherein adjacent resilient contact elements are spaced between 2.5 microns and 2000 microns from each other.

45. (New) The interconnect assembly according to claim 43, wherein

said substrate includes a redistribution trace formed therein, said redistribution trace providing said bond pad, said contact element thereby being conductively communicated with said redistribution trace.

46. (New) The interconnect assembly according to claim 43, wherein

said elongated contact structure is substantially triangularly shaped such that a width of said elongated contact structure adjacent said proximal end portion is substantially greater than a width of said elongated structure adjacent said distal end portion.

47. (New) The interconnect assembly according to claim 43, wherein

said distal end portion forms a pointed tip of said elongated contact structure.

48. (New) The interconnect assembly according to claim 43, wherein

a resiliency of said elongated contact structure is directly related to a thickness of said resilient material contact layer, wherein a relatively greater thickness of said resilient material contact layer yields a relatively increased resiliency.

49. (New) The interconnect assembly according to claim 43, wherein said distal end portion is formed with a beveled peripheral edge.

50. (New) An electrical system comprising:

a first substrate having an outwardly facing surface defining a bond pad;

a second substrate having a surface opposing and spaced from said outwardly facing surface;

said first substrate having a resilient contact element, said resilient contact element having a proximal end portion fixed relative to said outwardly facing surface and in communication with said bond pad, said resilient contact element including a resilient material contact layer and a conductive material contact layer;

said resilient contact element being formed by depositing an insulative material layer on said outwardly facing surface except said bond pad, depositing a conductive material layer on a portion of the insulative material layer in communication with said bond pad, depositing a sacrificial material layer on the insulative material layer, plating said resilient material contact layer on the sacrificial material layer in communication with the conductive material layer, plating said conductive material contact layer on said resilient material contact layer, and removing the sacrificial material layer;

a stop structure disposed between said first and second substrates and having a stop surface spaced from said outwardly facing surface;

said resilient contact element including an elongated contact structure extending from said proximal end portion, said elongated contact structure providing a distal end portion of said resilient contact element;

said distal end portion being in contact with said spaced opposing surface of said second substrate and being resiliently biased away from said outwardly facing surface by said elongated contact structure; and

said surface of said second substrate abutting said stop surface.

51. (New) The electrical system according to claim 50, wherein said first substrate comprises a plurality of said resilient contact elements, wherein adjacent resilient contact elements are spaced between 2.5 microns and 2000 microns from each other.

52. (New) The electrical system according to claim 50, wherein said spaced opposing surface of said second substrate defines a contact pad, said resilient contacting

element being in engagement with said contact pad such that said bond pad is conductively communicated with said contact pad.

53. (New) The electrical system according to claim 50, wherein said first substrate includes a redistribution trace formed therein, said redistribution trace providing said bond pad, said resilient contact element thereby being conductively communicated with said redistribution trace.

54. (New) The electrical system according to claim 50, wherein said elongated contact structure is substantially triangularly shaped such that a width of said elongated contact structure adjacent said proximal end portion is substantially greater than a width of said elongated structure adjacent said distal end portion.

55. (New) The electrical system according to claim 50, wherein said distal end portion forms a pointed tip of said elongated contact structure.

56. (New) The electrical system according to claim 50, wherein a resiliency magnitude of said elongated contact structure is directly related to a thickness of said resilient material contact layer, wherein a relatively greater thickness of said resilient material contact layer yields a relatively increased resiliency.

57. (New) The electrical system according to claim 50, wherein said distal end portion is formed with a beveled peripheral edge.